

Amendments to the Specification:

Please amend the paragraph commencing on page 14, line 4 and ending on page 14, line 15 as follows:

---- The reinforcing plate (18) is installed below the circuit board (14) to prevent the bend of the circuit board (14) and to attach the fixing structure (13) stably. This reinforcing plate (18) is formed with steel, ceramic or the same material with the fixing structure (13). The reinforcing plate (18), as illustrated in Figure 6, can be formed as the same size of the fixing structure (13) ~~(18)~~. Within the thickness range of about 1mm ~~[[~]]~~ through about 3cm, the ~~thick~~ thickness may be adjusted as required. In Figure 6, the electric wiring of the circuit board (14) has not been illustrated for convenience of the explanation as one skilled in the art will understand the electric wiring of the circuit board (14) and this explanation is not necessary for the purposes of understanding the present invention.---

Please replace the paragraph commencing on page 32, line 2 with the following new paragraph, and a replacement sheet showing the new paragraph for the abstract of the disclosure is attached.

---A probe card has probe sections with silicon probes formed on an insulated circuit board that are connected by an adhesive on the supporting structures. The supporting structures are supported by fixing structures with each of the fixing structures being fixed on the circuit board. The probe card has the probe section's wiring and the circuit board's wiring being electrically connected by a metallic wiring and the sub printed circuit and the pogo pin electrically connected by an anisotropic

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conducting film with the sub printed circuit board and the pogo pin. A metallic layer is formed by the plating of the probe in the probe section. This reduces the manufacturing costs by enabling the damaged probes during manufacturing to be discarded and the others being used continually.----